

ON Semiconductor®

FDD8453LZ-F085

N-Channel Power Trench[®] MOSFET 40V, 50A, 6.5m Ω

Features

- Typ $r_{DS(on)}$ = 5m Ω at V_{GS} = 10V, I_D = 15A
- Typ $r_{DS(on)}$ = 6m Ω at V_{GS} = 4.5V, I_D = 13A
- HBM ESD protection level > 7kv typical
- RoHS Compliant
- Qualified to AEC Q101

General Description

This N-Channel MOSFET is produced using ON Semiconductor's advanced PowerTrench® process that has been especially tailored to minimize the on-state resistance and switching loss. G-S zener haS been added to enhance ESD voltage level.

Applications

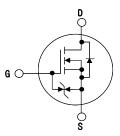
- Inverter
- Synchronous Rectifier



Package



Symbol



MOSFET Maximum Ratings $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Ratings	Units
V_{DSS}	Drain to Source Voltage	40	V
V_{GS}	Gate to Source Voltage	±20	V
1	Drain Current - Continuous (Package limited) T _C = 25°C	50	Α
'D	-Pulsed	Figure4	A
E _{AS}	Single Pulse Avalanche Energy (Note 1) 88	mJ
D	Power Dissipation	118	W
P_{D}	Dreate above 25°C	0.79	W/oC
T_J , T_{STG}	Operating and Storage Temperature	-55 to + 175	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance Junction to Case	1.27	°C/W
$R_{\theta JA}$	Thermal Resistance Junction to Ambient, 1in ² copper pad area	52	°C/W

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDD8453LZ	FDD8453LZ-F085	D-PAK(TO-252)	13"	12mm	2500 units

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted

Parameter

Off Characteristics							
B _{VDSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	40	-	-	V	
	Zara Cata Valtaga Drain Current	$V_{DS} = 32V,$	-	-	1		

Test Conditions

Min

Тур

Max

Units

B _{VDSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0V$	40	-	-	V
I _{DSS} Zero Gate	Zero Gate Voltage Drain Current	V _{DS} = 32V,	-	-	1	цΑ
	Zero Gate Voltage Drain Current	$V_{GS} = 0V$ $T_C = 150^{\circ}C$	-	-	250	μΑ
I _{GSS}	Gate to Source Leakage Current	V _{GS} = ±20V	-	-	±10	uA

On Characteristics

Symbol

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	1.0	1.8	3.0	V
		I _D = 15A, V _{GS} = 10V	-	5.0	6.5	mΩ
r _{DS(on)}	Drain to Source On Resistance	I _D = 13A, V _{GS} = 4.5V	-	6.0	7.8	mΩ
, ,		$I_D = 15A, V_{GS} = 10V T_J = 175^{\circ}C$	-	9.4	12.2	mΩ
g _{FS}	Forward Transconductance	$V_{DS} = 5V, I_{D} = 15A$	-	91	-	S

Dynamic Characteristics

C _{iss}	Input Capacitance	V 00V/V	0) /	-	2935	-	pF
Coss	Output Capacitance		$V_{DS} = 20V, V_{GS} = 0V,$ f = 1MHz		340	-	pF
C _{rss}	Reverse Transfer Capacitance	1 - 11VII 12			260	-	pF
R _g	Gate Resistance	f = 1MHz		-	1.8	-	Ω
$Q_{g(ToT)}$	Total Gate Charge at 10V	V _{GS} = 0 to 10V	V _{DD} = 20V	-	60	78	nC
Q _{g(5)}	Total Gate Charge at 5V	$V_{GS} = 0$ to 5V	I _D = 15A	-	32	42	nC
Q_{gs}	Gate to Source Gate Charge		I _g =1mA	-	7.5	-	nC
Q_{gd}	Gate to Drain "Miller" Charge			-	13	-	nC

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units

Switching Characteristics

t _{on}	Turn-On Time	V_{DD} = 20V, I_{D} = 15A, V_{GS} = 10V, R_{GEN} = 6 Ω	-	-	34	ns
t _{d(on)}	Turn-On Delay Time		-	12	-	ns
t _r	Rise Time		-	10	-	ns
t _{d(off)}	Turn-Off Delay Time		-	43	-	ns
t _f	Fall Time		-	7	-	ns
t _{off}	Turn-Off Time		-	-	80	ns

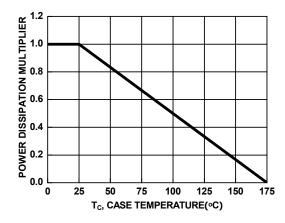
Drain-Source Diode Characteristics

V_{SD}	Source to Drain Diode Voltage	I _{SD} = 2A	-	0.7	1.2	V
		I _{SD} = 15A	-	0.8	1.3	V
t _{rr}	Reverse Recovery Time	-I _F = 15A, dI _{SD} /dt = 100A/μs	-	25	33	ns
Q _{rr}	Reverse Recovery Charge		1	14	19	nC

1: Starting T_J = 25°C, L = 0.11mH, I_{AS} = 40A, V_{DD} = 36V during inductor charging and V_{DD} = 0V during the time in Avalanche.

This product has been designed to meet the extreme test conditions and environment demanded by the automotive industry. For a copy of the requirements, see AEC Q101 at: http://www.aecouncil.com/
All ON Semiconductor products are manufactured, assembled and tested under ISO9000 and QS9000 quality systems certification.

Typical Characteristics



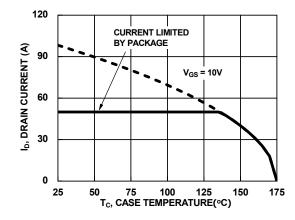
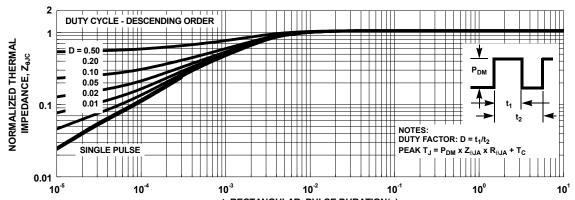


Figure 1. Normalized Power Dissipation vs Case Temperature

Figure 2. Maximum Continuous Drain Current vs Case Temperature



t, RECTANGULAR PULSE DURATION(s)
Figure 3. Normalized Maximum Transient Thermal Impedance

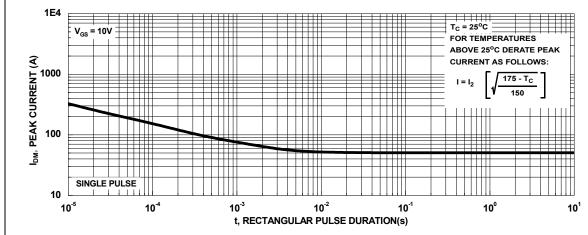


Figure 4. Peak Current Capability

Typical Characteristics

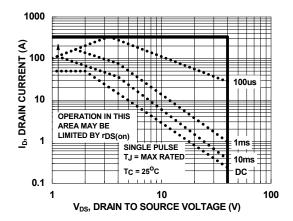
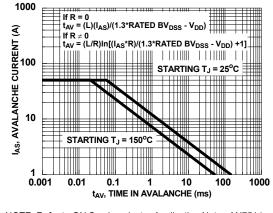


Figure 5. Forward Bias Safe Operating Area



NOTE: Refer to ON Semiconductor Application Notes AN7514 and AN7515

Figure 6. Unclamped Inductive Switching Capability

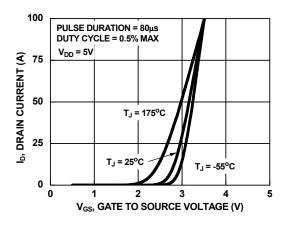


Figure 7. Transfer Characteristics

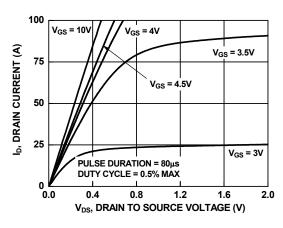


Figure 8. Saturation Characteristics

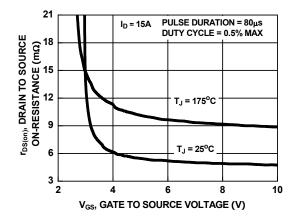


Figure 9. Drain to Source On-Resistance Variation vs Gate to Source Voltage

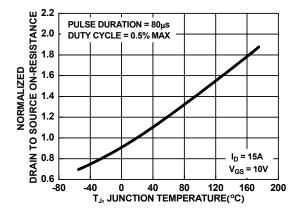


Figure 10. Normalized Drain to Source On Resistance vs Junction Temperature

Typical Characteristics

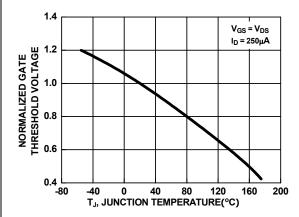


Figure 11. Normalized Gate Threshold Voltage vs
Junction Temperature

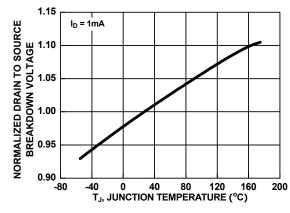


Figure 12. Normalized Drain to Source Breakdown Voltage vs Junction Temperature

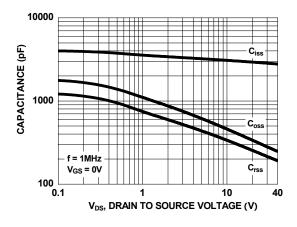


Figure 13. Capacitance vs Drain to Source Voltage

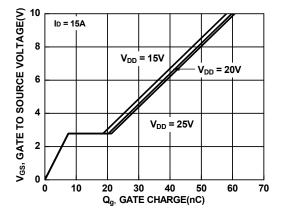


Figure 14. Gate Charge vs Gate to Source Voltage

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